

#### **Features**

- High Shock & Vibration Design
- AT-Cut Fundamental & Overtone Modes
- 100% Screening per MIL-PRF-3098, Class B
- Made in USA, ECCN: EAR99

### **Applications**

- High Shock & Vibration Applications
- Navigation Systems
- Aerospace Instrumentation
- Military & Defense

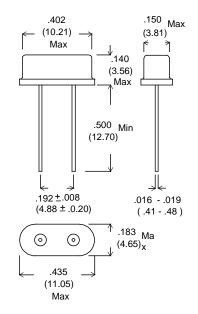
### **Package Specifications & Outline:**

- Cover Material: Nickel Silver
- Lead & Base Material & Finish: Kovar, 2 to 5 µm Min. Nickel Plate
- Weight: 1.0g typical, 1.4g Max.
- Seal: Hermetic Resistance Weld
- Solder Reflow, Temp./Time: 260 °C Max for 10 Seconds Max.

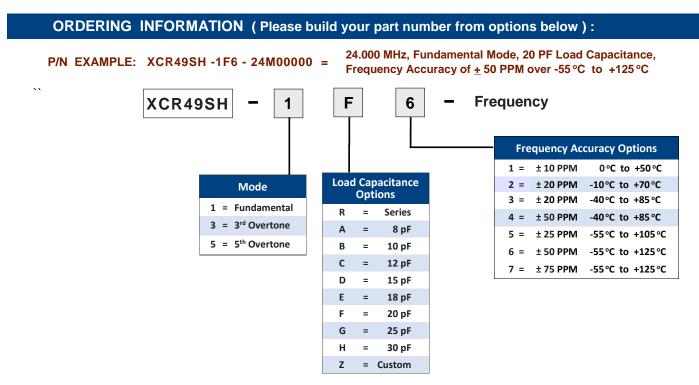
Hot Solder Tinning per MIL-PRF-55310 is optional at additional cost.

Contact Xsis Electronics at xsis@xsis.com for any special requirements.





Dimensions: Inches (mm)



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# Table I - Electrical Specifications, Fundamental, and 3rd Overtone Oscillation modes

| Parameter  | Fundamental   | 3 <sup>rd</sup>             |
|--|---|-----------------------------|
| Nominal Frequency Range  | 5.0 MHz to 30.0 MHz   | 25.0 MHz to 90.0 MHz        |
| Mode   | Fundamental   | 3 <sup>rd</sup>             |
| Resonance Type   | See Ordering Information on Page 1  |                             |
| Load Capacitance   | See Ordering Information on Page 1  |                             |
| Frequency Accuracy Vs. Temperature   | See Ordering Information on Page 1  |                             |
| Resistance (ESR)   5.00 to 6.00 MHz   6.01 to 8.00 MHz   8.01 to 10.00 MHz   10.01 to 15.00 MHz   15.01 to 30.00 MHz   25.00 to 50.00 MHz   50.01 to 90.00 MHz | 100 Ohms Max.<br>80 Ohms Max.<br>70 Ohms Max.<br>60 Ohms Max.<br>40 Ohms Max. | 80 Ohms Max.<br>70 Ohms Max |
| Shunt Capacitance  | 7 pF Max.   |                             |
| Unwanted Modes Resistance  | > 2 times the Main Mode Resistance  |                             |
| Storage Temperature  | -55 °C to +125 °C   |                             |
| Drive Level  | 50 μW Typical, 1 mW Max.  |                             |
| Aging at 25°C per year   | ± 3 PPM Max   |                             |

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### Table II - Environmental Specifications :

Crystal Units shall be able to withstand any of the following environmental stresses with change in Frequency of less than 5 PPM and change in resistance of less than 10%.

| Test - Inspection   | Test Method - Condition  |
|---------------------|--|
| Shock               | MIL-STD-202, Method 213, Cond. C                                       |
| Vibration           | MIL-STD-202, Method 204, Cond. A, 3 hours minimum.                     |
| Thermal Shock       | MIL-STD-202, Method 107, Cond. B                                       |
| Moisture Resistance | MIL-STD-202, Method 106, except Step 7b, Vibration, is not applicable. |

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## Table III - 100% Screening per MIL-PRF-3098, Class B

| Test - Inspection                                   | Test Method – Condition  |
|---|--|
| Pre-seal Visual Examination                         | MIL-PRF-3098, Method 4.10.2.2  |
| Stabilization Bake ( Prior to Seal ) /              | MIL-STD-883, Method 1008, Condition C<br>( +150 °C ), 24 hours minimum |
| Seal (Fine and Gross Leak)                          | MIL-PRF-3098, Para. 4.10.26  |
| Frequency and Resistance over Operating Temperature | MIL-PRF-3098, Para. 4.10.18  |
| External Visual & Mechanical                        | MIL-PRF-3098, Para. 4.10.2.1   |

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### **Table IV - Environmental**

XCR49SH series crystal units are designed to meet or exceed the Environmental tests specified below. Customized screening and environmental testing are also available to meet your special requirements.

| Test                          | Test Conditions   |
|-------------------------------|---|
| Mechanical Shock:             | 3000G, 0.5 mS shock.  |
| Vibration, Random:            | 20G RMS, 10 Hz to 2000 Hz   |
| Thermal Shock:                | MIL-STD-202, Method 107, Condition B                                      |
| Temperature Cycle:            | MIL-STD-883, Method, 1010, Condition B                                    |
| Moisture Resistance:          | MIL-STD-202, Method 106   |
| Salt Atmosphere:              | MIL-STD-202, Method 101   |
| Acceleration:                 | MIL-STD-883, Method 2002, Condition A, 5000G                              |
| Terminal Strength:            | MIL-STD-202, Method 211. Cond. A ( 2 pounds )                             |
| Fine Leak:                    | MIL-STD-202, Method 112, Condition C-IIIc (1x10 <sup>-8</sup> atm-cc/sec) |
| Gross Leak:                   | MIL-STD-202, Method 112, Condition D                                      |
| Solderability:                | MIL-STD-202, Method 208 ( ANSI-EIA-J-STD-002 )                            |
| Resistance to Soldering Heat: | MIL-STD-202, Method 210, Condition B or C                                 |
| Resistance to Solvents:       | MIL-STD-202, Method 215   |
| Low Temperature Storage:      | MIL-PRF-3098  |